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ON Semiconductor®

FDC3535

P-Channel Power Trench $^{\circledR}$ MOSFET -80 V, -2.1 A, 183 m Ω

Features

- Max $r_{DS(on)}$ = 183 m Ω at V_{GS} = -10 V, I_D = -2.1 A
- Max $r_{DS(on)}$ = 233 m Ω at V_{GS} = -4.5 V, I_D = -1.9 A
- High performance trench technology for extremely low r_{DS(on)}
- High power and current handling capability in a widely used surface mount package
- Fast switching speed
- 100% UIL Tested
- RoHS Compliant

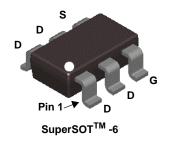


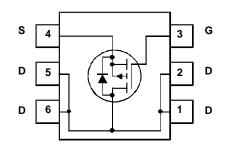
General Description

This P-Channel MOSFET is produced using ON Semiconductor's advanced Power Trench® process that has been optimized for $r_{DS(on)}$, switching performance and ruggedness.

Applications

- Load Switch
- Synchronous Rectifier





MOSFET Maximum Ratings T_A = 25 °C unless otherwise noted

Symbol	Parameter		Ratings	Units
V_{DS}	Drain to Source Voltage		-80	V
V_{GS}	Gate to Source Voltage		±20	V
	Drain Current -Continuous	(Note 1a)	-2.1	۸
ID	-Pulsed		-10	A
E _{AS}	Single Pulse Avalanche Energy	(Note 3)	37	mJ
P _D	Power Dissipation	(Note 1a)	1.6	10/
	Power Dissipation	(Note 1b)	0.7	W
T _J , T _{STG}	Operating and Storage Junction Temperature Range		-55 to +150	°C

Thermal Characteristics

$R_{\theta JC}$	Thermal Resistance, Junction to Case	30	°C/W
$R_{\theta JA}$	Thermal Resistance, Junction to Ambient (Note 1a)	78	C/VV

Package Marking and Ordering Information

Device Marking	Device	Package	Reel Size	Tape Width	Quantity
.535	FDC3535	SSOT-6	7 "	8 mm	3000 units

Electrical Characteristics $T_J = 25 \, ^{\circ}\text{C}$ unless otherwise noted

Parameter

Off Characteristics								
BV _{DSS}	Drain to Source Breakdown Voltage	I _D = -250 μA, V _{GS} = 0 V	-80			V		
$\Delta BV_{DSS} \over \Delta T_{J}$	Breakdown Voltage Temperature Coefficient	I_D = -250 μA, referenced to 25 °C		-64		mV/°C		
I _{DSS}	Zero Gate Voltage Drain Current	V _{DS} = -64 V, V _{GS} = 0 V			-1	μΑ		
I _{GSS}	Gate to Source Leakage Current	$V_{GS} = \pm 20 \text{ V}, V_{DS} = 0 \text{ V}$			±100	nA		

Test Conditions

On Characteristics

Symbol

V _{GS(th)}	Gate to Source Threshold Voltage	$V_{GS} = V_{DS}, I_{D} = -250 \mu A$	-1	-1.6	-3	V
$\frac{\Delta V_{GS(th)}}{\Delta T_J}$	Gate to Source Threshold Voltage Temperature Coefficient	I_D = -250 μ A, referenced to 25 °C		5		mV/°C
		$V_{GS} = -10 \text{ V}, I_D = -2.1 \text{ A}$		147	183	
r _{DS(on)}	Static Drain to Source On Resistance	$V_{GS} = -4.5 \text{ V}, I_D = -1.9 \text{ A}$		176	233	mΩ
		$V_{GS} = -10 \text{ V}, I_D = -2.1 \text{ A}, T_J = 125 \text{ °C}$		246	307	
9 _{FS}	Forward Transconductance	$V_{DD} = -10 \text{ V}, I_D = -2.1 \text{ A}$		6.3		S

Dynamic Characteristics

C _{iss}	Input Capacitance	V 40 V V 0 V	659	880	pF
C _{oss}	Output Capacitance	$V_{DS} = -40 \text{ V}, V_{GS} = 0 \text{ V},$ $f = 1 \text{ MHz}$	49	65	pF
C _{rss}	Reverse Transfer Capacitance	1 - 1 101112	24	40	pF
R _a	Gate Resistance		5.7		Ω

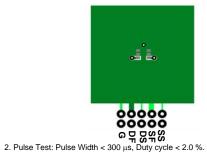
Switching Characteristics

t _{d(on)}	Turn-On Delay Time		6.5	13	ns
t _r	Rise Time	V _{DD} = -40 V, I _D = -2.1 A,	3.1	10	ns
t _{d(off)}	Turn-Off Delay Time	$V_{GS} = -10 \text{ V}, R_{GEN} = 6 \Omega$	23	38	ns
t _f	Fall Time		2.9	10	ns
0	Total Gate Charge	V _{GS} = 0 V to -10 V	14	20	nC
$Q_{g(TOT)}$	Total Gate Charge	$V_{GS} = 0 \text{ V to } -4.5 \text{ V}$ $V_{DD} = -40 \text{ V}$	6.8	10	nC
Q _{gs}	Total Gate Charge	I _D = -2.1 A	1.6		nC
Q_{gd}	Gate to Drain "Miller" Charge		2.7		nC

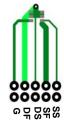
Drain-Source Diode Characteristics

V_{SD}	Source to Drain Diode Forward Voltage	$V_{GS} = 0 \text{ V}, I_{S} = -2.1 \text{ A}$ (Note 2)	-0.81	-1.3	V
t _{rr}	Reverse Recovery Time	I _E = -2.1 A. di/dt = 100 A/us	25	40	ns
Q _{rr}	Reverse Recovery Charge	1F = -2.1 A, αι/αι = 100 A/μS	23	38	nC

1. $R_{\theta JA}$ is the sum of the junction-to-case and case-to-ambient thermal resistance where the case thermal reference is defined as the solder mounting surface of the drain pins. $R_{\theta JC}$ is guaranteed by design while $R_{\theta CA}$ is determined by the user's board design.



a. 78 °C/W when mounted on a 1 in² pad of 2 oz copper



b.175 °C/W when mounted on a minimum pad of 2 oz copper

Тур

Max

Units

- 3. Starting T $_{J}$ = 25 $^{o}C,\,L$ = 3 mH, I $_{AS}$ = -5 A, V $_{DD}$ = -80 V, V $_{GS}$ = -10 V.

Typical Characteristics T_J = 25 °C unless otherwise noted

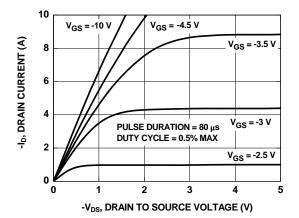


Figure 1. On-Region Characteristics

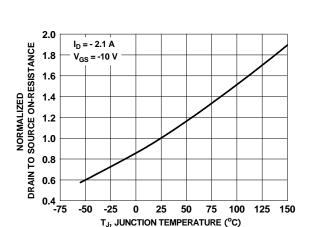


Figure 3. Normalized On-Resistance vs Junction Temperature

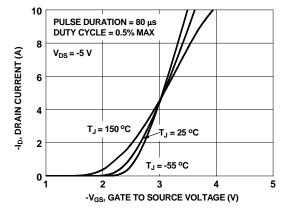


Figure 5. Transfer Characteristics

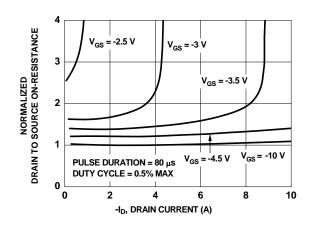


Figure 2. Normalized On-Resistance vs Drain Current and Gate Voltage

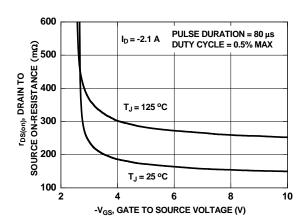


Figure 4. On-Resistance vs Gate to Source Voltage

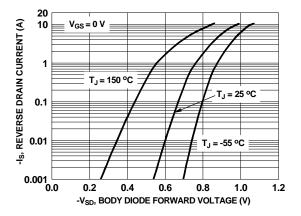


Figure 6. Source to Drain Diode Forward Voltage vs Source Current

Typical Characteristics $T_J = 25$ °C unless otherwise noted

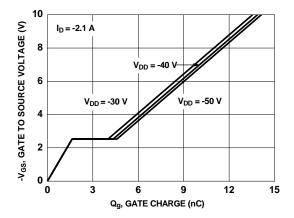


Figure 7. Gate Charge Characteristics

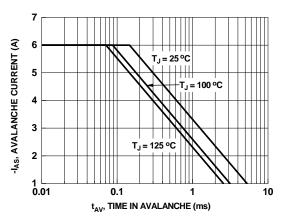


Figure 9. Unclamped Inductive Switching Capability

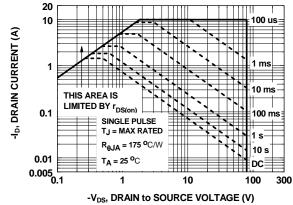


Figure 11. Forward Bias Safe
Operating Area

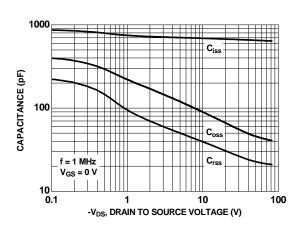


Figure 8. Capacitance vs Drain to Source Voltage

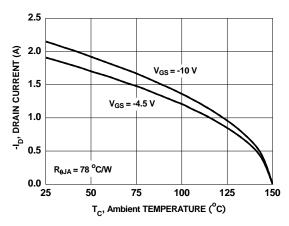


Figure 10. Maximum Continuous Drain Current vs Ambient Temperature

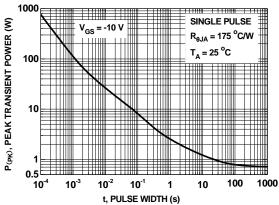


Figure 12. Single Pulse Maximum Power Dissipation

Typical Characteristics T_J = 25 °C unless otherwise noted

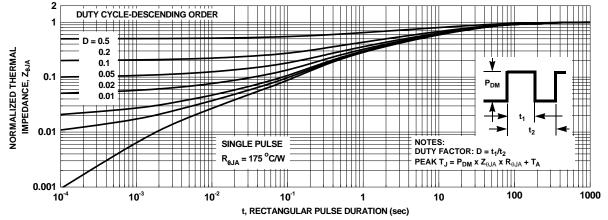


Figure 13. Junction-to-Ambient Transient Thermal Response Curve

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